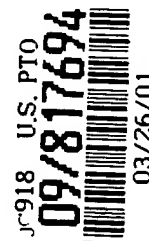


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**Navarro IP Law Group, P.C.**

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801 E. Campbell Road  
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gary.honeycutt@iplaw-group.com



March 23, 2001

**VIA EXPRESS MAIL**

Assistant Commissioner for Patents  
Washington, D.C. 20231

EL690653937US

Re: Patent Application For  
**Fixture and Method for Uniform Electroless Metal Deposition on  
Integrated Circuit Bonds Pads.**  
Attorney Docket No. TI-30592  
Our File: 1000-2141

Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Non-Provisional Application/Fee Authorization/transmittal Form ;
- (2) Declaration, and Power of Attorney;
- (3) Recordation Form Cover Sheet with Assignment;
- (4) Specifications and Formal Drawings; and
- (5) Postcards.

Please charge **Deposit Account No. 20-0668** in the amount of the total fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to **Deposit Account No. 20-0668**.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely

A handwritten signature in cursive script that reads "Gary C. Honeycutt".  
Gary C. Honeycutt  
Reg. No. 20,230

GCH/ntn  
Enclosure

03/26/01 41 U.S. PTO

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)  
TRANSMITTAL FORM

Attorney Docket No. TI-30589

Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the  
patent application of:

Inventor(s): **Gonzalo Amador**  
**Roger J. Stierman**

"EXPRESS MAILING" Mailing Label No.  
EL690653937US. Date of Deposit: March 23,  
2001. I hereby certify that this paper is being  
deposited with the U.S. Postal Service Express  
Mail Post Office to Addressee Service under 37  
CFR 1.10 on the date shown above and is  
addressed to the Assistant Commissioner for  
Patents, Washington, D.C. 20231.

Nancy Thornton 3/23/2001

For: **Fixture and Method for Uniform Electroless Metal Deposition on Integrated Circuit Bond Pads**

Enclosed are:

- 2 Sheets of formal drawings and 18 pages of Specification (including Abstract)  
X A Declaration/Power of Attorney  
X Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 based upon **Provisional Patent  
Application number 60/193,615, filed 03/31/2000.**

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 710.00
Total Claims	11	- 20 =	0	X \$22 =	\$0.00
Independent Claims	2	- 3 =	0	X \$82 =	\$0.00
Total Filing Fee					\$710.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The  
Commissioner is hereby authorized to charge any additional fees which may be required, or credit  
any overpayment to Deposit Account No. 20-0668. **This form is submitted in triplicate.**

All correspondence related to this application may be addressed to the undersigned at Navarro IP  
Law Group, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: March 23, 2001

*Gary C. Honeycutt*  
Gary C. Honeycutt  
Registration No. 20,250